

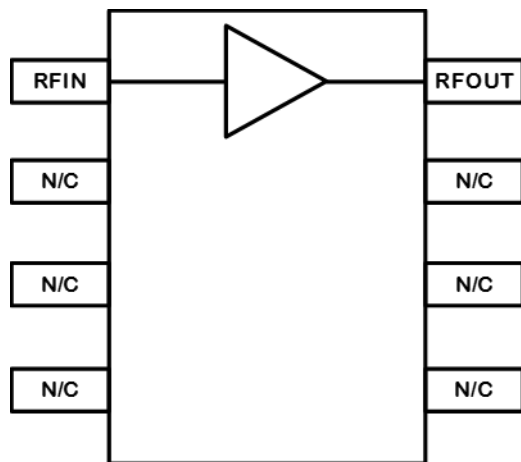
Product Overview

The QPB3311 is an HBT single ended RF amplifier IC operating as return path amplifier capable of supporting DOCSIS 3.1 applications. This IC is designed to provide a low noise, high gain option for 5-210MHz interface using an 8V power supply to provide lower overall power dissipation. 5V operation is possible in applications with reduced linearity and gain requirements. The QPB3311 is packaged in a convenient SOIC8 package and features an externally adjustable bias control.



Package: SOIC-8 with Exposed Pad

Functional Block Diagram



Top View

Key Features

- 5MHz to 210MHz Operation
- 8V and 5V Operation
- Gain; 15.3dB Typical
- Noise Figure 3.8dB Typical
- Adjustable Bias Using External Resistors
- SOIC-8 Exposed Pad

Applications

- Head End CMTS Equipment
- Post Amp for Return Path Optical Receivers
- DOCSIS 3.1 Optical Nodes
- Residential Amplifiers and Splitters

Ordering Information

| Part No. | Description |
|-------------|---------------------------------------|
| QPB3311SQ | Sample bag with 25 pieces |
| QPB3311SR | 7" Reel with 100 pieces |
| QPB3311TR13 | 13" Reel with 2500 pieces |
| QPB3311PCK | 5 – 210 MHz PCBA with 5 pc sample bag |

Absolute Maximum Ratings

| Parameter | Rating |
|--|----------------|
| Supply Voltage (V_{DD}) | +10V |
| Supply Current (I_{DD}) | 275mA |
| Maximum CW Input Power for $V_{DD}=8V$ | +16dBm |
| Operating Temperature Range | -40 to +85 °C |
| Storage Temperature Range | -65 to +150 °C |
| Maximum Junction Temperature | +150 °C |

Exceeding any one or a combination of the Absolute Maximum Rating conditions may cause permanent damage to the device. Extended application of Absolute Maximum Rating conditions to the device may reduce device reliability.

Electrical Specifications – 8V

| Parameter | Condition ⁽¹⁾ | Min | Typ | Max | Unit |
|-----------------------------|--|-----|-------|-----|------|
| Supply Voltage (V_{DD}) | | | 8 | | V |
| Supply Current (I_{DD}) | | | 172 | | mA |
| Frequency Range | | 5 | | 210 | MHz |
| Gain | 50MHz | | 15.3 | | dB |
| Gain Flatness | | | ±0.2 | | dB |
| Gain Tilt | Gain(210MHz) - Gain(5MHz) | | -0.10 | | dB |
| Input Return Loss | Full Band | | 15 | | dB |
| Output Return Loss | Full Band | | 20 | | dB |
| Reverse Isolation | Full Band | | 19 | | dB |
| Noise Figure | Includes balun loss | | 3.8 | | dB |
| DTO | f1=13MHz, f2=19MHz 58dBmV per tone | | 80 | | -dBc |
| DSO | f1=13MHz, f2=19MHz 58dBmV per tone | | 60 | | -dBc |
| ACLR | Pout = 61dBmV, 5-195MHz OFDM w/ 9.6MHz exclusion band. | | 63 | | dB |
| OIP2 | 9dBm/tone, F1 = 113MHz, F2 = 119MHz | | 69 | | dBm |
| OIP3 | 9dBm/tone, F1 = 113MHz, F2 = 119MHz | | 48 | | dBm |
| Output P1dB | Full Band | | 23.5 | | dBm |
| Thermal Resistance | Θ_{JC} | | 28 | | °C/W |

Notes:

1. Typical performance at these conditions: Temp = +25°C, V_{DD} = +8V, 75Ω system



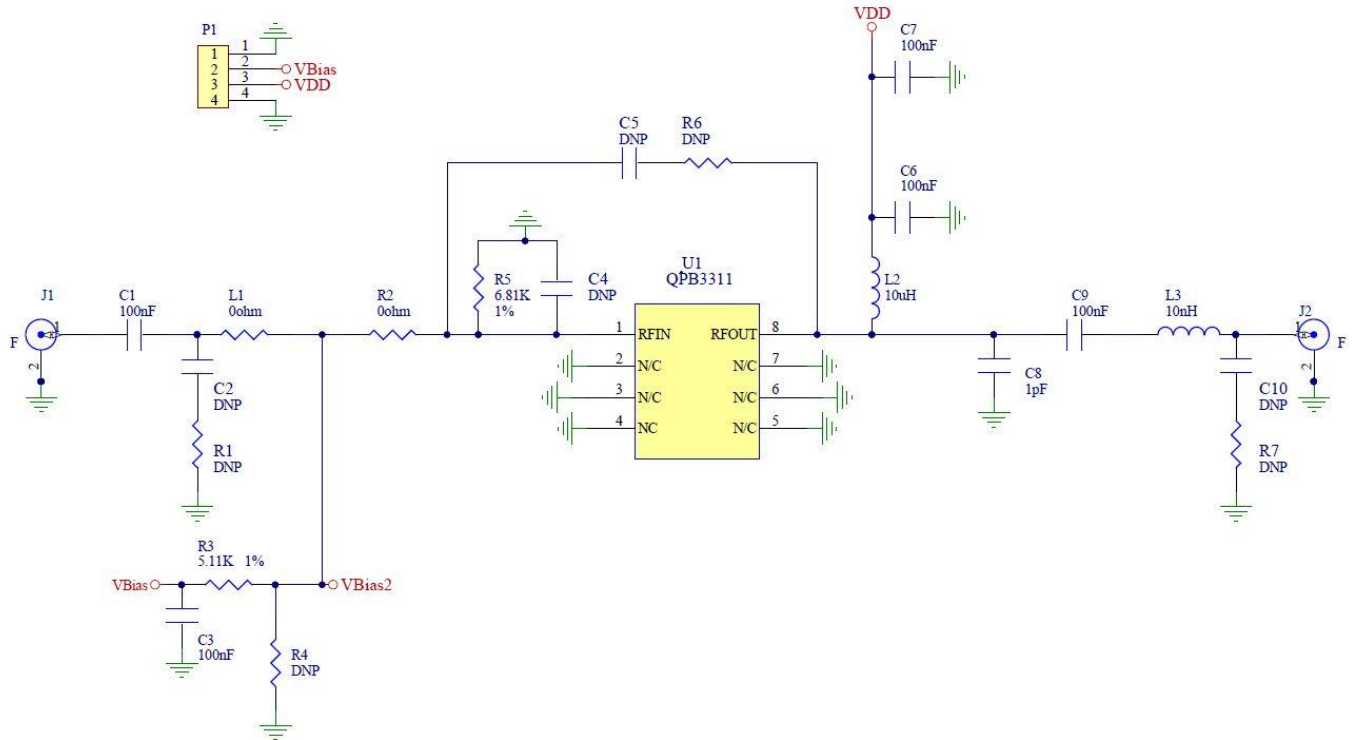
Electrical Specifications – 5V

| Parameter | Condition ⁽¹⁾ | Min | Typ | Max | Unit |
|-----------------------------|--|-----|-----------|-----|------|
| Supply Voltage (V_{DD}) | | | 5 | | V |
| Supply Current (I_{DD}) | | | | | mA |
| Frequency Range | | 5 | | 210 | MHz |
| Gain | Full Band | | 13.5 | | dB |
| Gain Flatness | | | ± 0.2 | | dB |
| Gain Tilt | Gain(210MHz) - Gain(5MHz) | | -0.1 | | dB |
| Input Return Loss | Full Band | | 22 | | dB |
| Output Return Loss | Full Band | | 21 | | dB |
| Reverse Isolation | Full Band | | 20 | | dB |
| Noise Figure | Full Band | | 5.0 | | dB |
| DTO | f1=13MHz, f2=19MHz 55dBmV per tone | | 76 | | -dBc |
| DSO | f1=13MHz, f2=19MHz 55dBmV per tone | | 55 | | -dBc |
| ACLR | Pout = 53dBmV, 5-195MHz OFDM w/ 9.6MHz exclusion band. | | 62 | | dB |
| OIP2 | 6dBm/tone, F1 = 113MHz, F2 = 119MHz | | 54 | | dBm |
| OIP3 | 6dBm/tone, F1 = 113MHz, F2 = 119MHz | | 39 | | dBm |
| Output P1dB | Full Band | | 18.6 | | dBm |

Notes:

1. Typical performance at these conditions: Temp = +25°C, V_{DD} = +5V, 75Ω system

Evaluation Board Schematic 5-210MHz





QPB3311

15 dB Return Path Amplifier 5 – 210 MHz

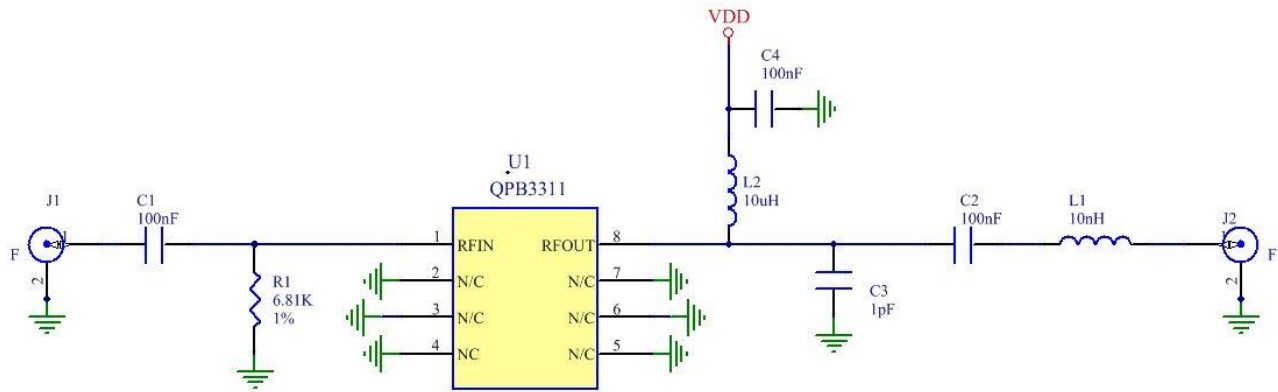
Evaluation Board Bill of Materials

| Designator | Description | Manufacturer | Part Number |
|---------------------------------|------------------------------------|-------------------------------------|--------------------|
| PCB | QPB3311-4000 | DDI | QPB3311-4000(A) |
| C1, C3, C6, C7, C9 | CAP, 0.1uF, 10%, 16V, X7R, 0402 | Murata Electronics | GRM155R71C104KA88D |
| C8 | CAP, 1.0pF, ±0.1pF, 50V, NPO, 0402 | Murata Electronics | GRM1555C1H1R0BZ01D |
| J1, J2 | CONN, F FEM EDGE MOUNT, 75 OHMS | Millimeter Wave Technologies, LLC | MW-846-C-DD-75 |
| L1, R2 | JMPR, 0 OHM, 0402 | Panasonic | ERJ-2GE0R00 |
| L2 | IND, 10uH, 10%, 500mA, W/W, 1210 | Murata | 82103C |
| L3 | IND, 10nH, 5%, M/L, 0402 | Murata Electronics | LQG15HN10NJ02D |
| P1 | CONN, HDR, ST, FRCTN LOCK, 4-PIN | Molex | 22-23-2041 |
| R3 | RES, 5.11K, 1%, 1/16W, 0402 | Cal-Chip Electronics | RM04F5111CT |
| R5 | RES, 6.81K, 1%, 1/16W, 0402 | Panasonic | ERJ-2RKF6811X |
| U1 | 15dB High-Linearity MMIC | Qorvo | QPB3311 |
| C2, C4, C5, C10, R1, R4, R6, R7 | DNP | N/A | N/A |
| HS1 | Heat Sink 1.5 x 2 | Shenzhen Minxingda Automation Equip | 211086 |
| S1, S2, S3, S4 | Screw, 2-56x3/16:, Socket Head | McMaster-Carr Supply Co. | 92196A076 |

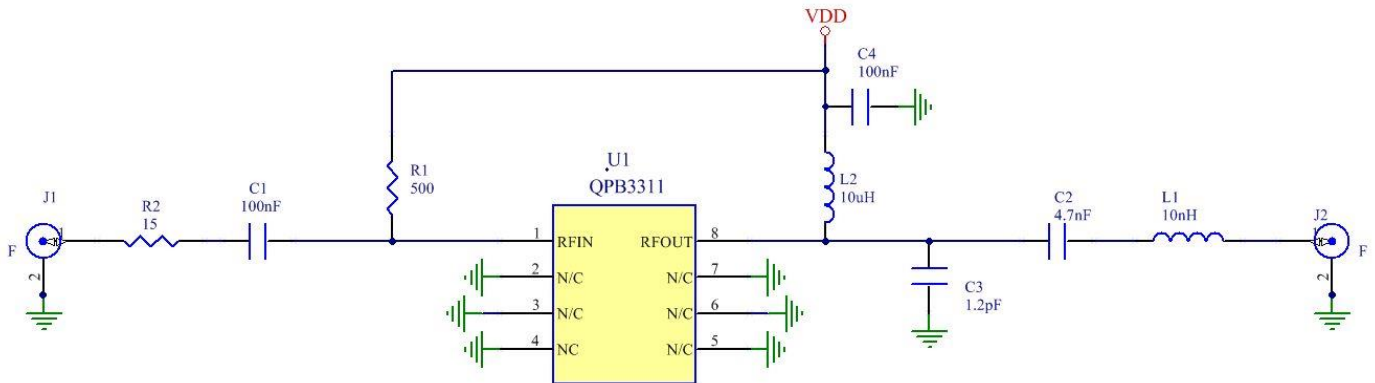
Evaluation Board Assembly Drawing



Typical Application Schematic, 8V



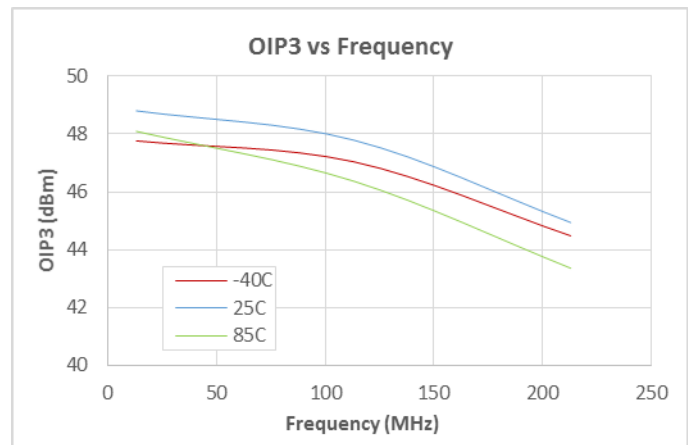
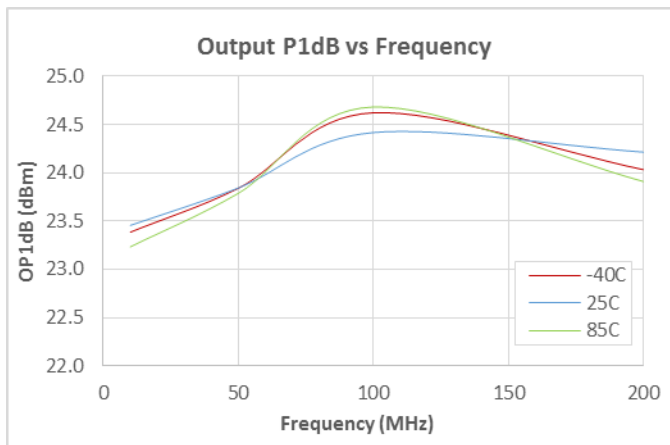
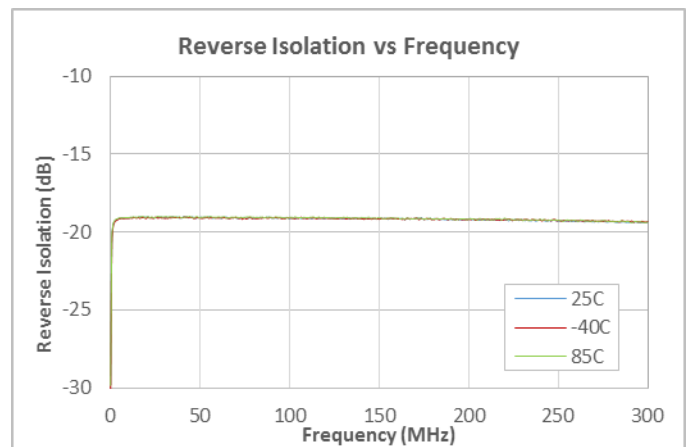
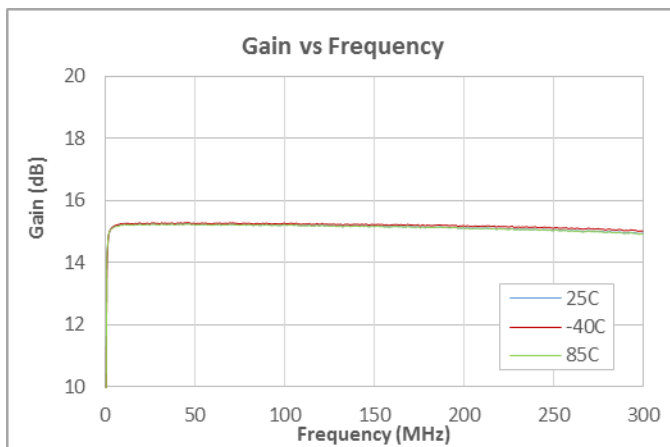
Typical Application Schematic, 5V



Notes:

1. R2 can be reduced for improved noise figure (will degrade input return loss).
2. R1 increases bias current to recommended 100mA operating point for improved bias stability versus temperature.

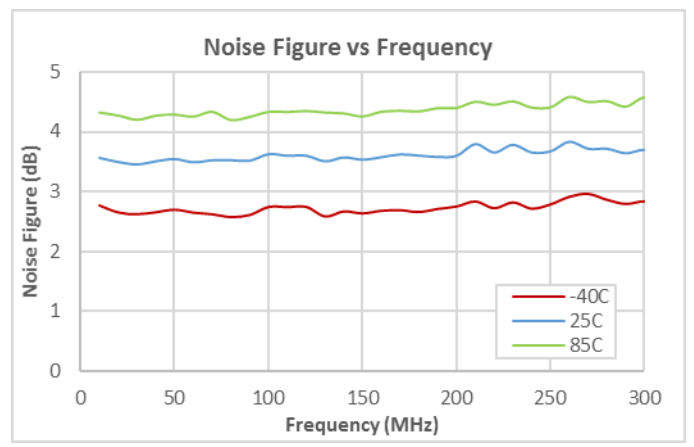
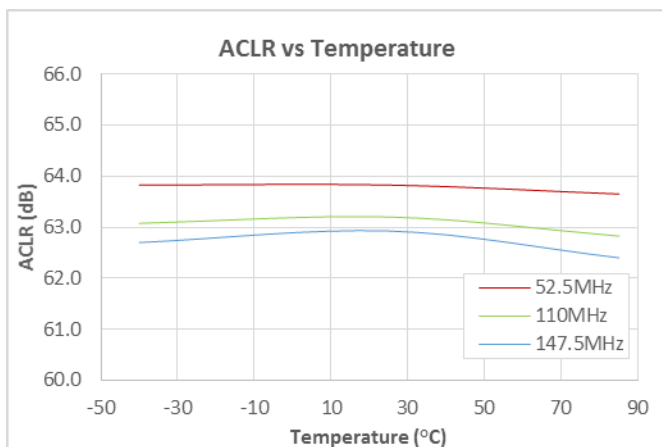
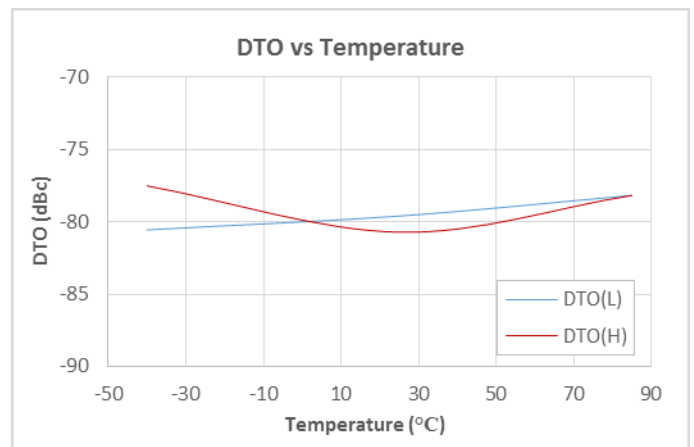
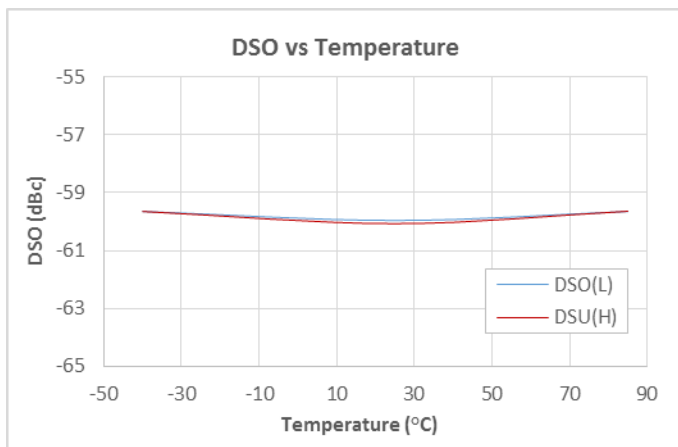
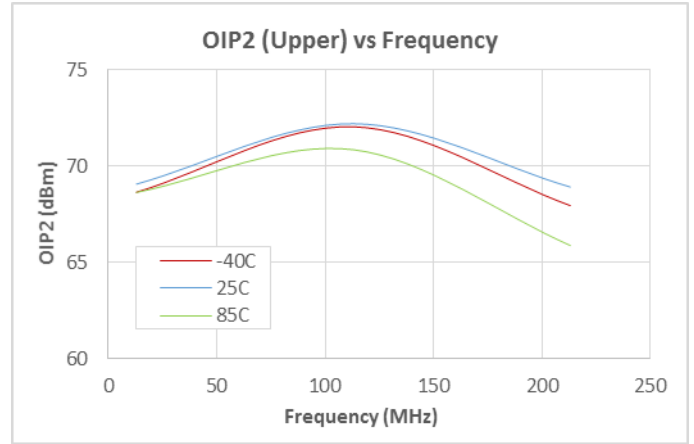
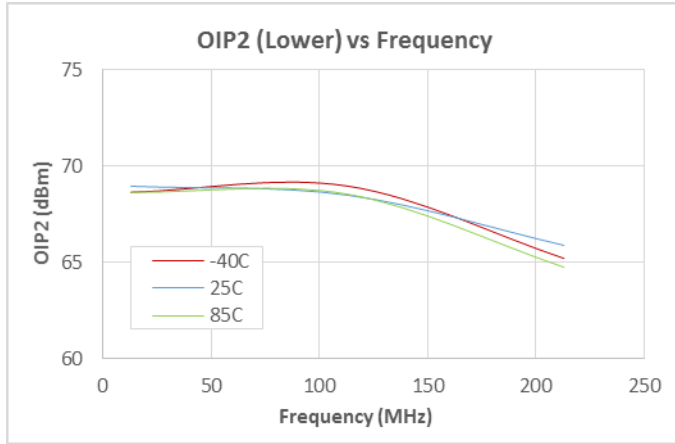
Performance Data – 8V



Notes:

- (1) OIP3: 9dBm/tone, F1 = 113MHz, F2 = 119MHz

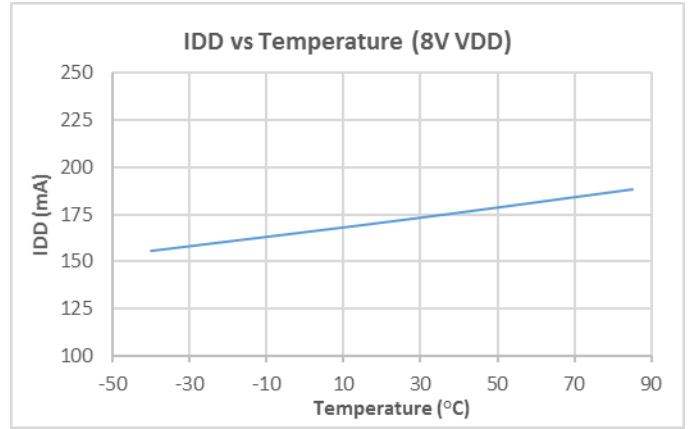
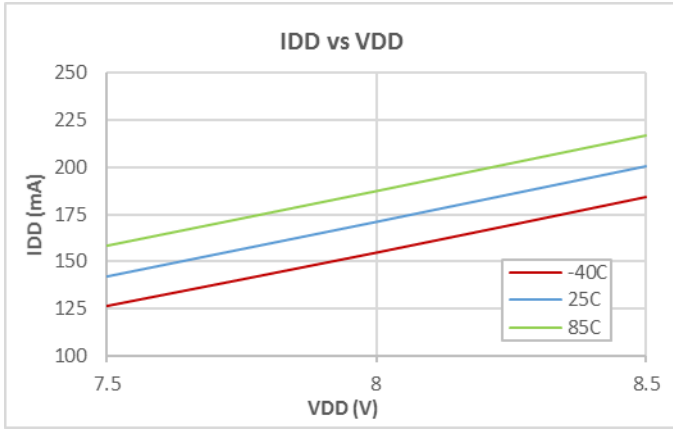
Performance Data – 8V



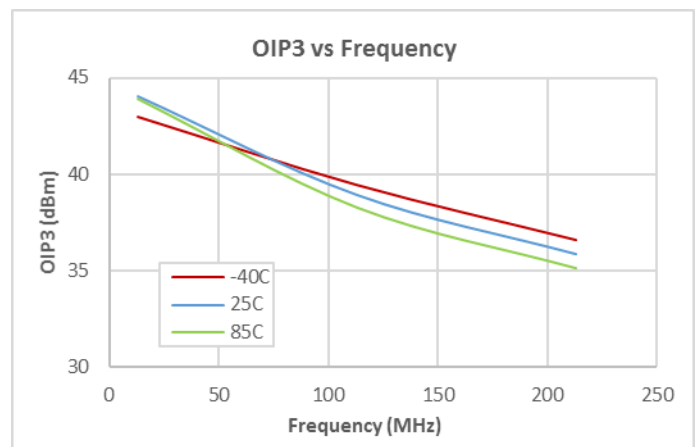
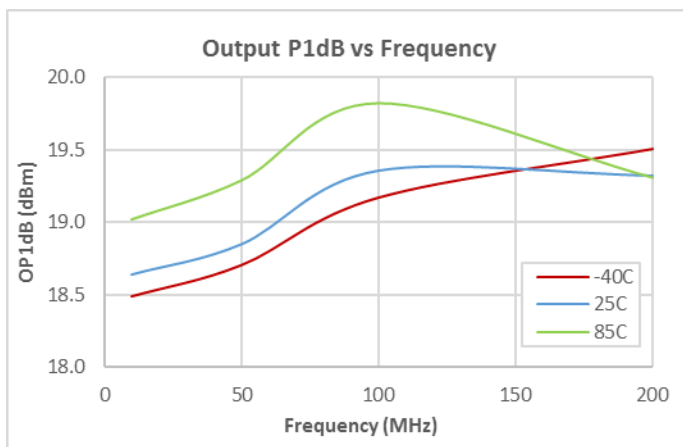
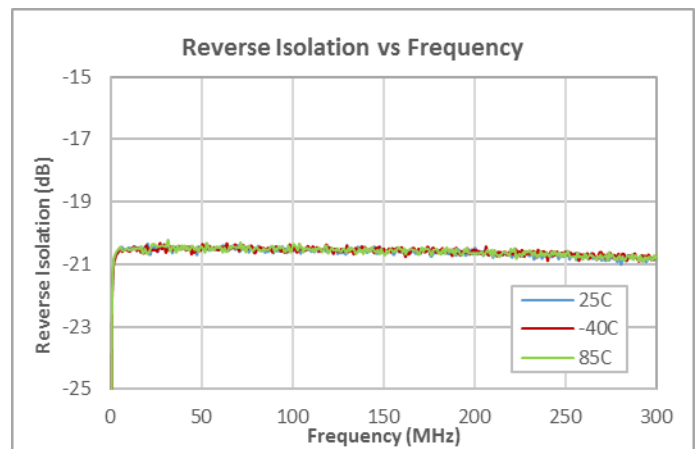
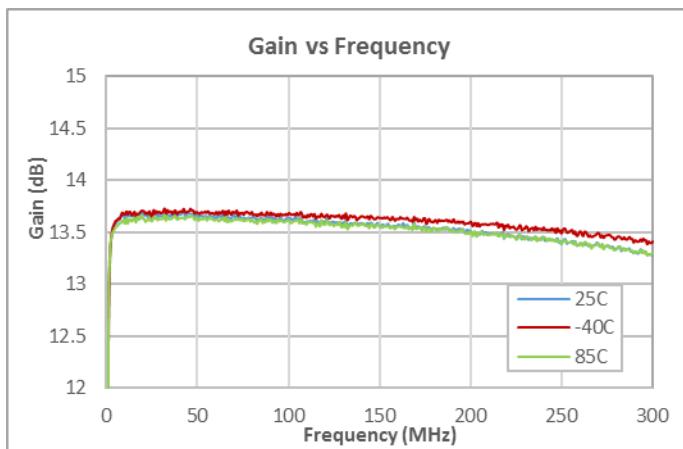
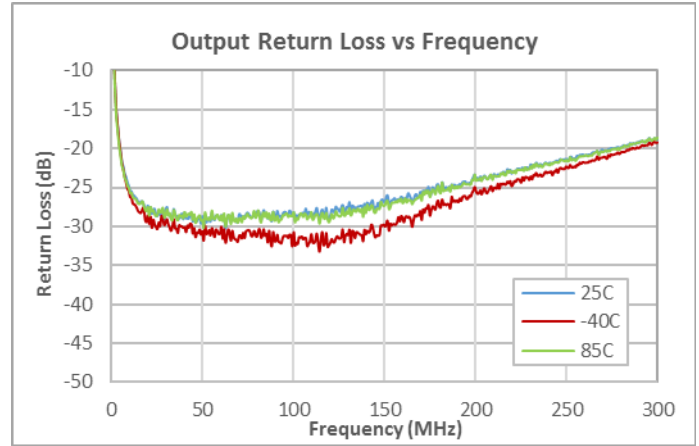
Notes:

- (2) OIP2: 9dBm/tone, F1 = 113MHz, F2 = 119MHz
- (3) DSO/DTO: f1=13MHz, f2=19MHz 58dBmV per tone
- (4) ACLR: Pout = 61dBmV, 5-195MHz OFDM w/ 9.6MHz exclusion band.

Performance Data – 8V



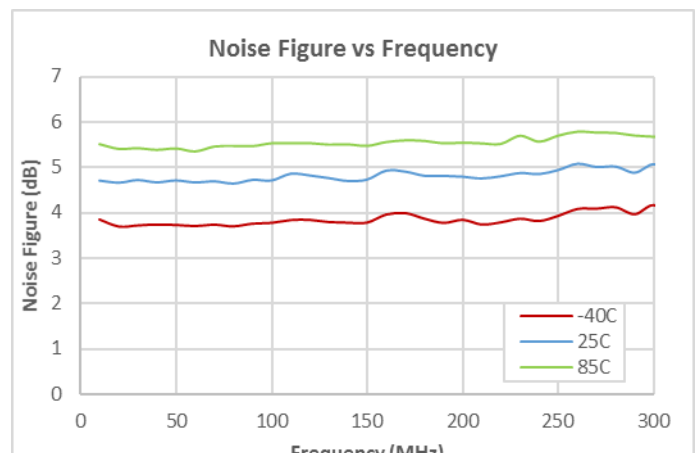
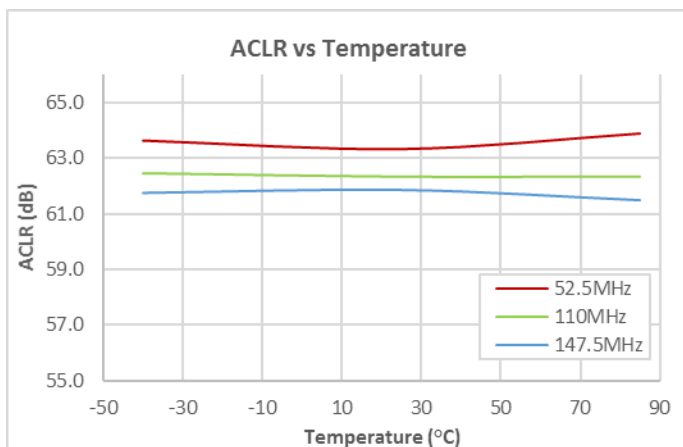
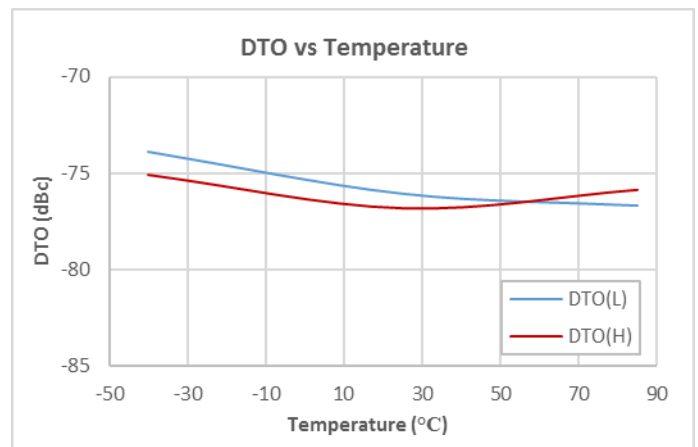
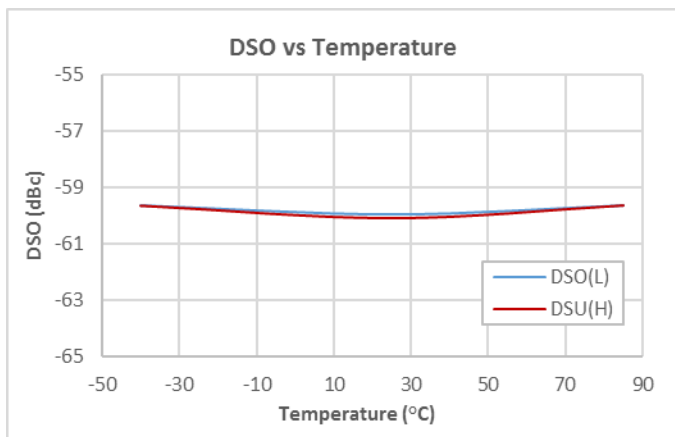
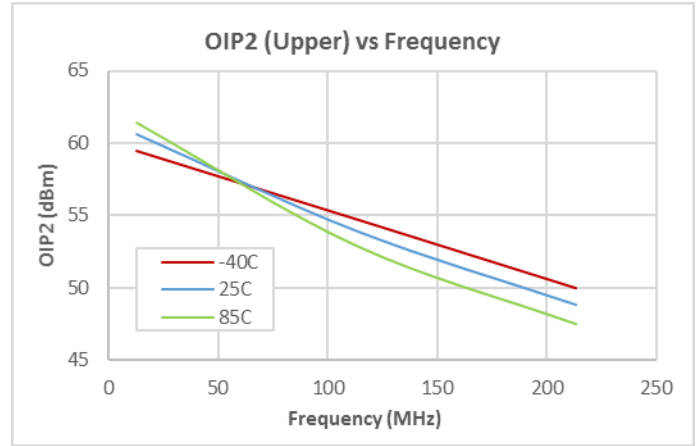
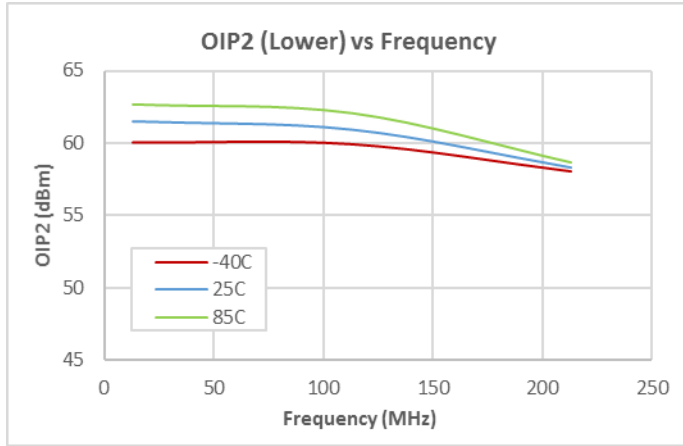
Performance Data – 5V



Notes:

- (1) OIP3: 6dBm/tone, F1 = 113MHz, F2 = 119MHz

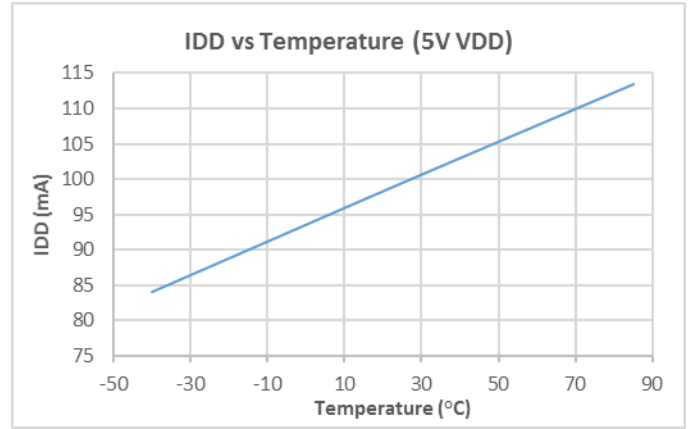
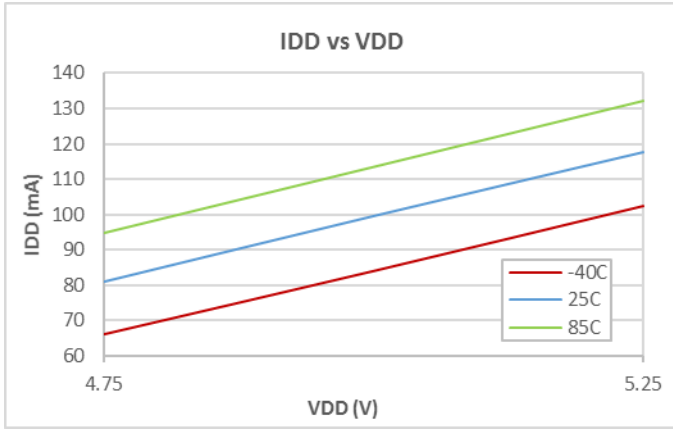
Performance Data – 5V



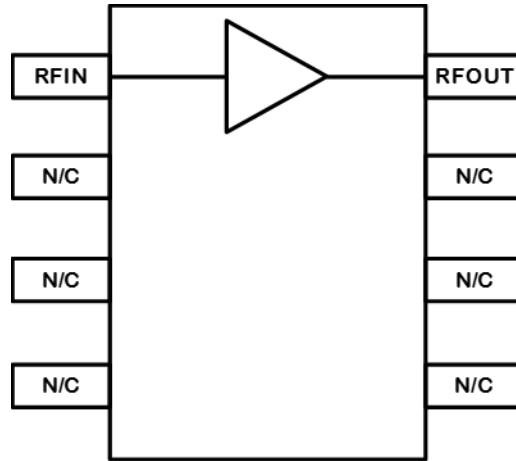
Notes:

- (1) OIP2: 6dBm/tone, F1 = 113MHz, F2 = 119MHz
- (2) DSO/DTO: f1=13MHz, f2=19MHz 55dBmV per tone
- (3) ACLR: Pout = 53dBmV, 5-195MHz OFDM w/ 9.6MHz exclusion band.

Performance Data – 5V



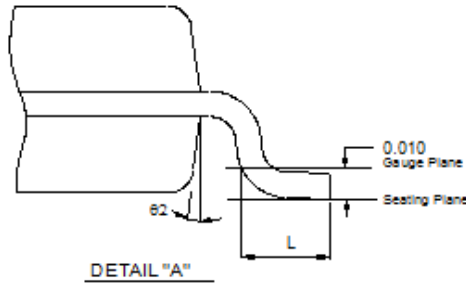
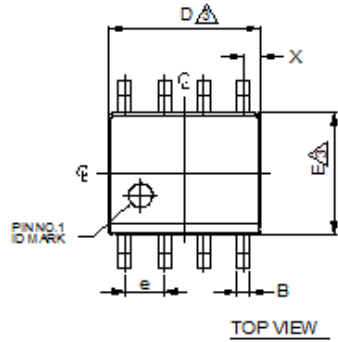
Pad Configuration and Description



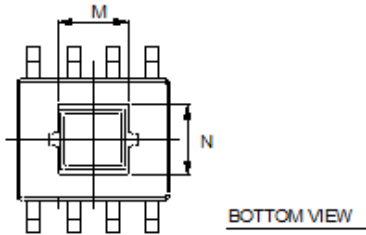
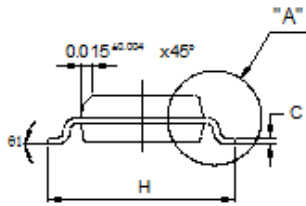
Top View

| Pad No. | Label | Description |
|-----------------|-------|--|
| 1 | RFIN | RF Input, 75Ω |
| 2 | N/C | Internally Not Connected |
| 3 | N/C | Internally Not Connected |
| 4 | N/C | Internally Not Connected |
| 5 | N/C | Internally Not Connected |
| 6 | N/C | Internally Not Connected |
| 7 | N/C | Internally Not Connected |
| 8 | RFOUT | RF Output, 75Ω |
| Backside Paddle | GND | Ground. Use recommended via pattern to minimize inductance and thermal resistance. See PCB Mounting Pattern for suggested footprint. |

Package Outline



| SYMBOL | 8 SOIC | |
|--------|------------|--------|
| | MIN | MAX |
| A | 0.054 | 0.068 |
| A1 | 0.001 | 0.004 |
| B | 0.014 | 0.019 |
| D | 0.189 | 0.196 |
| E | 0.150 | 0.157 |
| H | 0.229 | 0.244 |
| M | 0.087 | 0.097 |
| N | 0.082 | 0.092 |
| e | 0.050 BSC | |
| C | 0.0075 | 0.0098 |
| L | 0.020 | 0.040 |
| X | 0.0215 REF | |
| 61 | 0° | 8° |
| 62 | 7° BSC | |



EXPOSED PADDLE

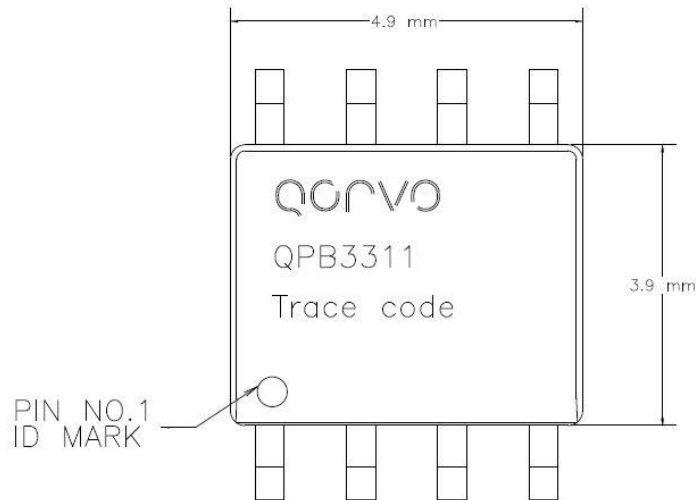
NOTE:

1. TOP PACKAGE SURFACE TO BE Ni, Pd, Au PLATING
2. BOTTOM PACKAGE SURFACE TO BE Ni, Pd, Au PLATING
3. DIMENSIONS ARE EXCLUSIVE MOLD FLASH AND GATE BURR.
4. FOOT LENGTH MEASURING IS BASED ON THE GAUGE PLANE METHOD.

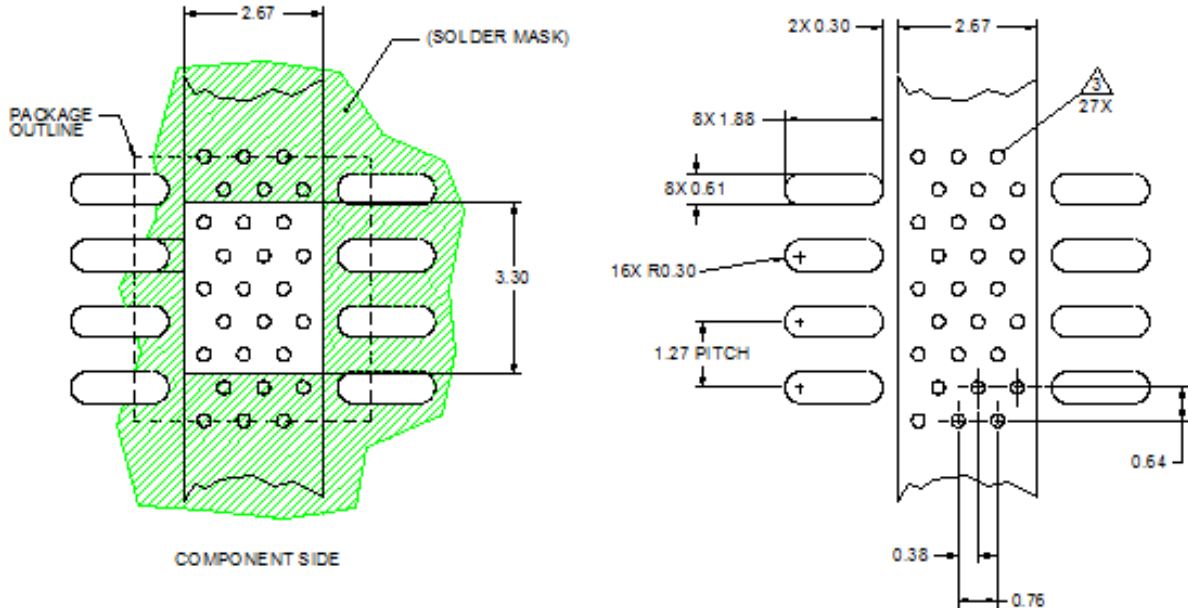
Notes:

1. Dimensions in millimeters

Package Marking



Recommended Mounting Pattern



Notes:

1. All dimensions are in millimeters. Angles are in degrees.
2. Use 1oz. copper minimum for top and bottom layers
3. Vias are required under the backside paddle for proper RF/DC grounding and thermal dissipation. We recommend a 0.35mm (#80/0.135") diameter bit for drilling via holes and a final plated through diameter of 0.25mm (0.010").
4. Ensure good backside paddle solder attach for reliable operation and best electrical performance.

Handling Precautions

| Parameter | Rating | Standard |
|----------------------------------|--------|--------------------------|
| ESD – Human Body Model (HBM) | 1B | ESDA / JEDEC JS-001-2012 |
| ESD – Charged Device Model (CDM) | C3 | JEDEC JESD22-C101F |
| MSL – Moisture Sensitivity Level | MSL3 | IPC/JEDEC J-STD-020 |



Caution!
ESD-Sensitive Device

Solderability

Compatible with both lead-free (260°C max. reflow temp.) and tin/lead (245°C max. reflow temp.) soldering processes. Solder profiles available upon request.

Contact plating: NiPdAu

RoHS Compliance

This part is compliant with 2011/65/EU RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment) as amended by Directive.

This product also has the following attributes:

- Lead Free
- Halogen Free (Chlorine, Bromine)
- Antimony Free
- TBBP-A (C₁₅H₁₂Br₄O₂) Free
- PFOS Free
- SVHC Free



Contact Information

For the latest specifications, additional product information, worldwide sales and distribution locations:

Tel: **1-844-890-8163**

Web: www.qorvo.com

Email: customer.support@qorvo.com

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- Поставка сложных, дефицитных, либо снятых с производства позиций;
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- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
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- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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